

# HSD88

Silicon Schottky Barrier Diode for Detector, Mixer

REJ03G0602-0100 (Previous: ADE-208-1386) Rev.1.00 Apr 26, 2005

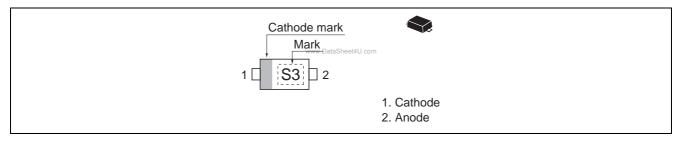
### Features

- Low capacitance. (C = 0.8 pF max)
- Low forward voltage.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

### **Ordering Information**

Type No.	Cathode Mark	Package Name	Package Code (Previous Code)
HSD88	S3	SFP	PUSF0002ZB-A (SFP)

### **Pin Arrangement**





## **Absolute Maximum Ratings**

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	10	V
Average rectified current	lo	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	٥C

### **Electrical Characteristics**

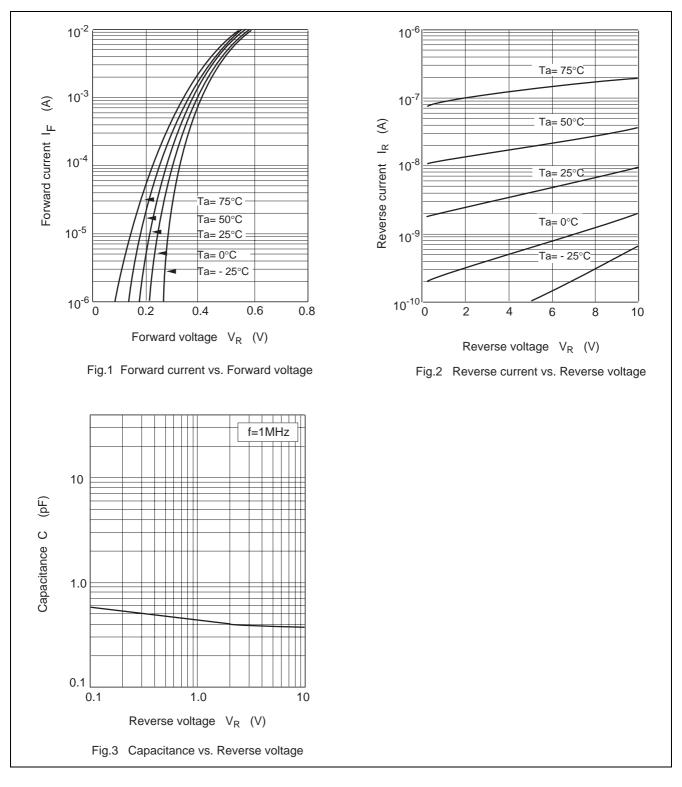
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F1</sub>	0.350	—	0.420	V	I <sub>F</sub> = 1 mA
	V <sub>F2</sub>	0.500	—	0.580		I <sub>F</sub> = 10 mA
Reverse current	I <sub>R1</sub>	_	_	0.2	μA	V <sub>R</sub> = 2 V
	I <sub>R2</sub>	_	—	10		V <sub>R</sub> = 10 V
Capacitance	С	_	—	0.80	pF	V <sub>R</sub> = 0 V, f = 1 MHz
ESD-Capability *1	—	30	_	_	Ω	C = 200 pF, Both forward and
						reverse direction 1 pulse.

Notes: 1. Failure criterion ;  $I_R > 0.4~\mu\text{A}$  at  $V_R$  = 2 V

2. Please do not use the soldering iron due to avoid high stress to the SFP package.

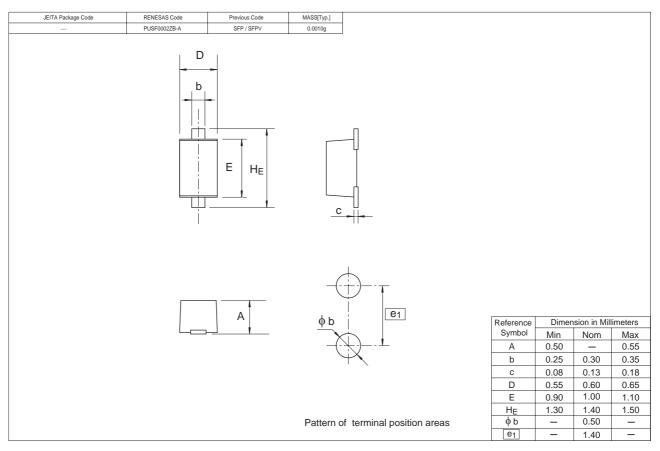


### **Main Characteristic**





# Package Dimensions





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